





RECOMMENDED SOLDER PAD LAYOUT **--** 1.00 [0.039] 2.50 [0.098] MIN. 2.00 [0.079] (2 PLS.)

NOTES:

- 1. PART SUPPLIED ON SUPER 8 TAPE AND REEL, 3,000 PIECES PER REEL.
- 2. THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.
- 3. WHITE CERAMIC CARRIER.

CAUTION: MOISTURE SENSITIVE DEVICE PER JEDEC LEVEL 4 STANDARDS

PART NUMBER CCL - CRS10SR

DEV E C NI NIIMBED AND DEVISION COMMENTS

REV.

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
А	REDRAWN.	4.27.00
В	CORRECTED DIMS.	3.20.95
С	E.C.N. #10390 & #10BRDR & REDRAWN.	10.2.98
D	E.C.N. #10484. ADDED SOLDER SPECS.	12.11.98
Е	E.C.N. #10695. & REDRAWN IN 3D.	12.28.00
F	E.C.N. #10967.	3.14.03

PARAMETER MIN TYP MAX UNITS	TEST COND
TAKAMETEK MIIN III MAX GNITS	
PEAK WAVELENGTH 660 nm	
FORWARD VOLTAGE 1.7 2.2 V _f	
REVERSE VOLTAGE 3.0 V _r	I _r =100μΑ
AXIAL INTENSITY 40 mcd	$I_f = 20mA$
VIEWING ANGLE 180 2x theta	
EMITTED COLOR: RED	
EPOXY LENS FINISH: WATER CLEAR	

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	60	mA
STEADY CURRENT	15	mA
POWER DISSIPATION	45	mW
DERATE FROM 25°C	33	mW/*C
OPERATING TEMP.	-30 TO + 75	•C
STORAGE TEMP.	-40 TO +85	°C
* t<10µS		

SOLDER HEAT PROOF TEST:	DIPPING FOR 5 SEC. AT 250°C, 2 TIMES.
THERMAL SHOCK TEST:	15 MIN. AT +90°C, AND 15 MIN. AT -30°C, 25 CYCLES.
VIBRATION TEST:	50Hz, FULL AMPLITUDE WIDTH; 1.5mm,
	2 HOURS VERTICALLY AND HORIZONTALLY, RESPECTIVELY.
MOISTURE TEST:	Ta=60°C, Rh=90%, 1,000 HOURS.
IRON SOLDERING:	20W IRON (SHARP TIP), 280-320°C, 5 SEC. MAX.,
SOLDER DIP METHODE:	TEMP. IS 240-260°C AND TIME IS WITHIN 10 SEC.
RE-FLOW SOLDERING:	SEE CHART.

UNCONTROLLED DOCUMENT *UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION MAX.= +0.00 (±0.005). LEAD SIZE=±0.05 (±0.005). LEAD S

PART NUMBER	
CCL - CRS10SR	

TAPE FEED DIRECTION -

TOP TAPE

REV.

3.0mm x 2.5mm CERAMIC SURFACE MOUNT LED. 660nm SUPER RED LED, WATER CLEAR LENS.

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RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

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APPROVED BY: DATE: CHECKED BY: 5.20.97 DRAWN BY: PAGE: 1 OF 1 SCALE: N/A